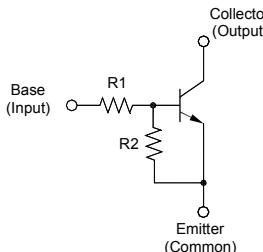


MMDTC114YHP

NPN Silicon Epitaxial Planar Digital Transistor

Features

- With built-in bias resistors
- Simplify circuit design
- Reduce a quantity of parts and manufacturing process



Bottom view
1. Base 2. Emitter 3. Collector
DFN1006-3H Plastic Package

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Collector Base Voltage	V_{CBO}	50	V
Collector Emitter Voltage	V_{CEO}	50	V
Base Emitter Voltage	V_{EBO}	10	V
Input Voltage	V_I	- 6 to + 40	V
Collector Current	I_C	100	mA
Peak Collector Current	I_{CM}	100	mA
Power Dissipation	P_{tot}	150	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	- 55 to + 150	°C

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Unit
DC Current Gain at $V_{CE} = 5 \text{ V}$, $I_C = 5 \text{ mA}$	h_{FE}	100	-	-	-
Collector Base Cutoff Current at $V_{CB} = 50 \text{ V}$	I_{CBO}	-	-	0.1	μA
Collector Emitter Cutoff Current at $V_{CE} = 30 \text{ V}$	I_{CEO}	-	-	1	μA
Emitter Base Cutoff Current at $V_{EB} = 5 \text{ V}$	I_{EBO}	-	-	150	μA
Collector Emitter Saturation Voltage at $I_C = 5 \text{ mA}$, $I_B = 0.25 \text{ mA}$	$V_{CE(sat)}$	-	-	0.1	V
Input on Voltage at $V_{CE} = 0.3 \text{ V}$, $I_C = 1 \text{ mA}$	$V_{I(on)}$	-	-	1.4	V
Input off Voltage at $V_{CE} = 5 \text{ V}$, $I_C = 100 \mu\text{A}$	$V_{I(off)}$	0.5	-	-	V
Collector Capacitance at $V_{CB} = 10 \text{ V}$, $f = 1 \text{ MHz}$	C_{ob}	-	-	2.5	pF
Transition frequency at $V_{CE} = 5 \text{ V}$, $-I_C = 10 \text{ mA}$, $f = 100 \text{ MHz}$	f_T	-	230	-	MHz
Input Resistance	R_1	7	10	13	kΩ
Resistance Ratio	R_2 / R_1	3.7	4.7	5.7	-

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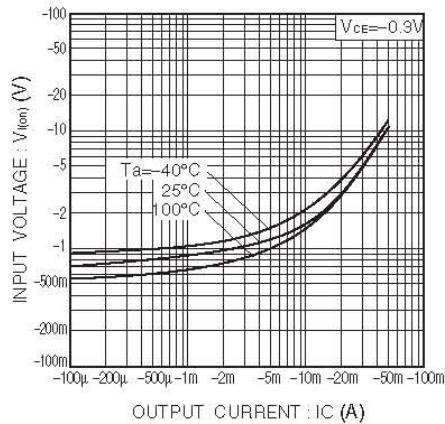


Fig.1 Input voltage vs. output current
(ON characteristics)

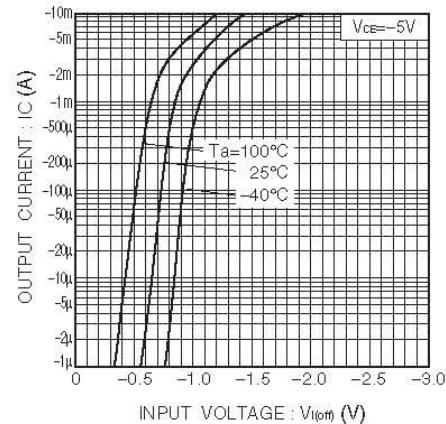


Fig.2 Output current vs. input voltage
(OFF characteristics)

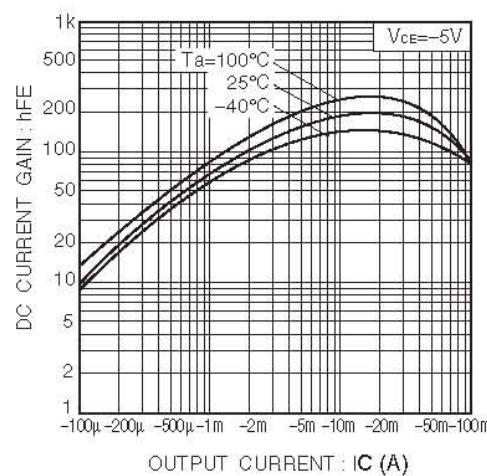


Fig.3 DC current gain vs. output current

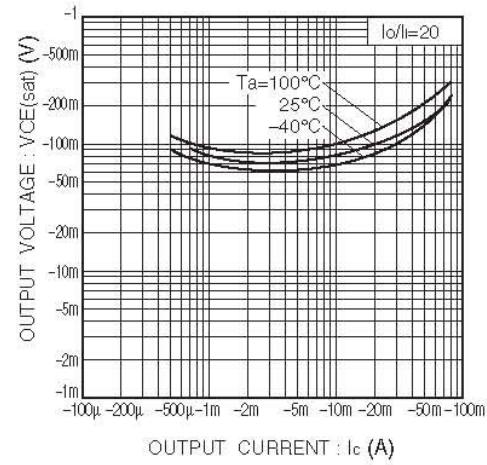


Fig.4 Output voltage vs. output current

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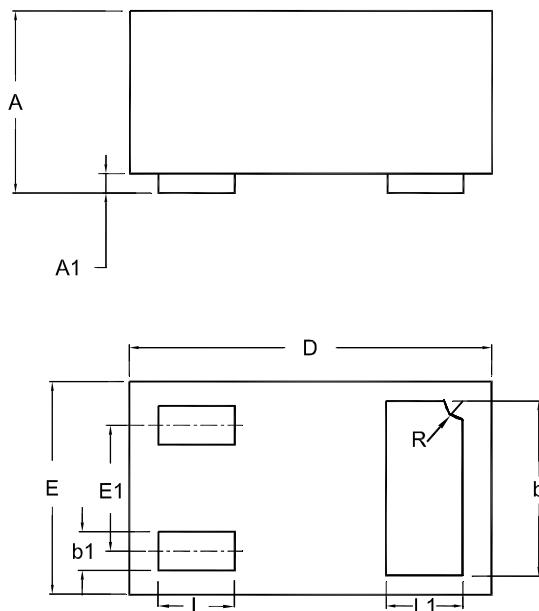
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PACKAGE OUTLINE

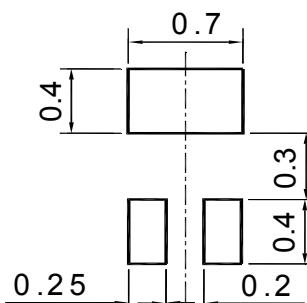
Plastic surface mounted package

DFN1006-3H



UNIT	A	A1	b	b1	D	E	E1	L	L1	R
mm	0.51	0.05	0.55	0.2	1.05	0.65	0.325	0.3	0.3	0.15
	0.46	0	0.45	0.1	0.95	0.55	0.2	0.2	0.2	0.05

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1006-3H	8	4 ± 0.1	0.157 ± 0.004	178	7	5,000

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ISO14001 : 2004 ISO 9001 : 2008 OHSAS 18001 : 2007 IECQ QC 080000

Certificate No. 121505007 Certificate No. 50114012 Certificate No. 05131506008 Certificate No. ESD-100114022

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